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## What is claimed is:

1. A high voltage semiconductor device, comprising:

a high concentration collector area of a first conductive type;

a low concentration collector area of a first conductive type formed on the high concentration collector area;

a base area of a second conductive type formed on the low concentration collector area and having a trench which penetrates the low concentration collector area in a vertical direction at the edge of the trench;

a high concentration emitter area of a first conductive type formed on a predetermined upper surface of the base area; and

an emitter electrode, a base electrode, and a collector electrode isolated from one another and connected to the emitter area, the base area, and the collector area, respectively.

- 2. The high voltage semiconductor device of claim 1, wherein the width of the trench is 1/10 times the depth of the trench.
- 3. The high voltage semiconductor device of claim 1, further comprising an oxide layer which fills the trench.
- 4. A method of fabricating a high voltage semiconductor device, comprising:

preparing a semiconductor substrate having a high concentration collector area and a low concentration collector area of a first conductive type;

forming a base area of a second conductive type on the low concentration collector area;

forming a high concentration emitter area of a first conductive type on a predetermined upper portion of the base area;

forming a trench penetrating the base area and the low concentration collector area at the edge of the base area, spaced apart from the emitter area; and

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forming an emitter electrode, a base electrode, and a collector electrode connected to the emitter area, the base area, and a semiconductor substrate, respectively.

- 5. The method of claim 4, wherein the trench is formed using a reactive ion etching method.
- 6. The method of claim 5, wherein the reactive ion etching is performed using  $Cl_2$  or  $SF_6$  as a reaction gas.
- 7. The method of claim 4, wherein the width of the trench is 1/10 times the depth of the trench.